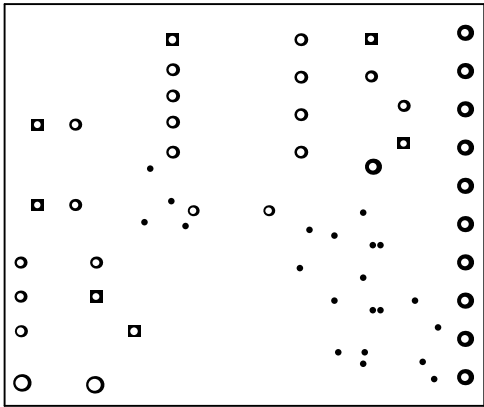
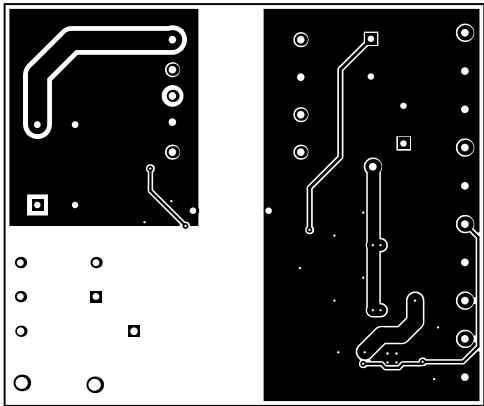


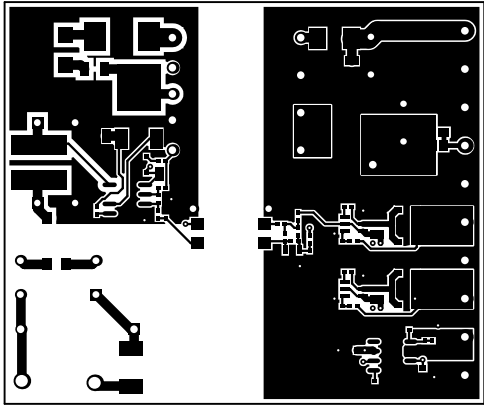
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/3/2014 2:31:21 PM	TEXAS INSTRUMENTS	



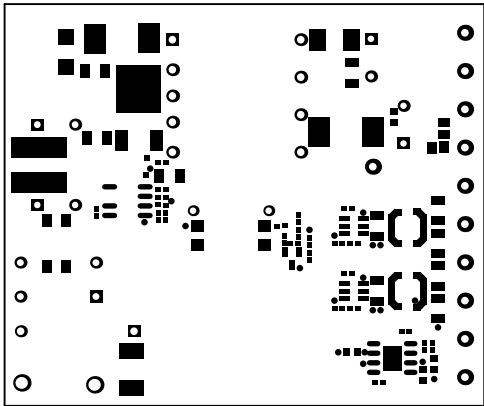
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/3/2014 2:31:21 PM	TEXAS INSTRUMENTS	



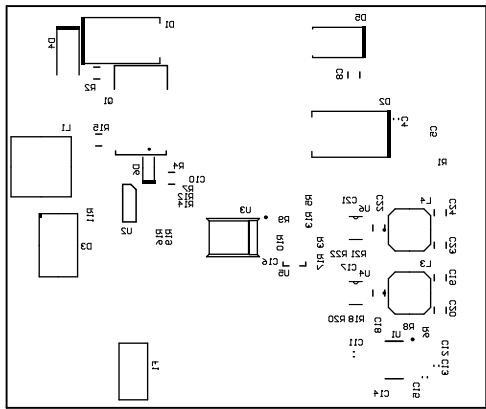
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
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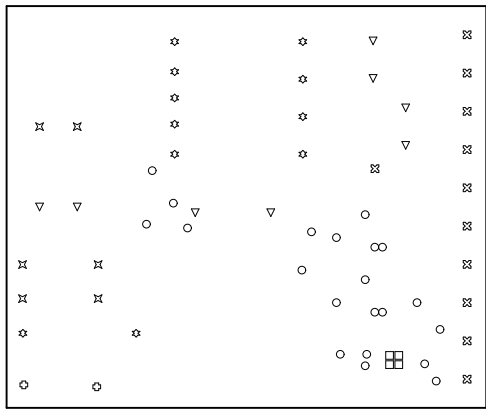
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/3/2014 2:31:23 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 4/3/2014 2:31:23 PM	TEXAS INSTRUMENTS	



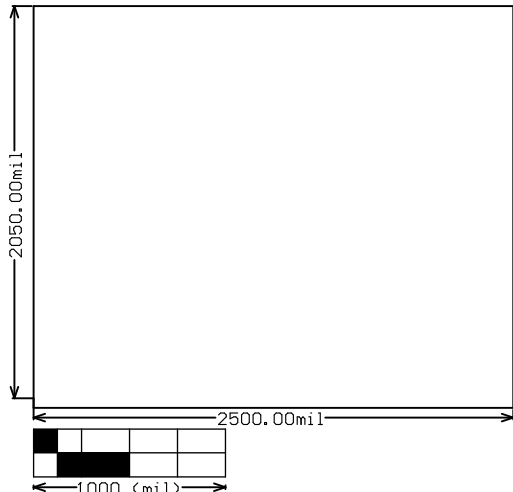
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/3/2014 2:31:24 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	21	12mil (0.305mm)	PTH	Round
□	4	12.992mil (0.33mm)	PTH	Round
▽	8	33.465mil (0.85mm)	PTH	Round
✕	6	35.433mil (0.9mm)	PTH	Round
☆	11	39.37mil (1mm)	PTH	Round
⊗	11	40mil (1.016mm)	PTH	Round
⊕	2	63mil (1.6mm)	PTH	Round
	63 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/3/2014 2:31:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9661	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/3/2014 2:31:26 PM	TEXAS INSTRUMENTS	

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